

Landau discloses apparatus and a method for electroplating a metal layer onto a substrate, the apparatus being described most generally in the paragraph bridging columns 4 and 5 of this patent. As for the chemistry of the electrodeposition, note column 17, lines 41-44 and 57-59; and column 18, lines 12-15, of this patent. As for operating condition, see columns 15-17 of this patent.

Barstad, et al., and Gerenrot, et al., have been previously discussed.

Even assuming, arguendo, that the teachings of Barstad, et al., and Gerenrot, et al., were properly combinable with the teachings of Landau, such combined teachings would have neither disclosed nor would have suggested the presently claimed bath and process, including wherein the solution of the bath contains both the additive (e.g., at least one of the compounds represented by the general formula (I)) and the at least one of polyethers, organic sulfur compounds and halide ions, and advantages thereof, as discussed previously; and, more specifically, those further features of the components as in claims 15, 16 and 21-24.

In addition, with respect to the contention by the Examiner that Barstad, et al., discloses a plating bath containing a halide ion source, attention is respectfully directed to claims 17-20; it is respectfully submitted that the teachings of the applied prior art would have neither disclosed nor would have suggested these features of the present invention.

In view of the foregoing comments and amendments, reconsideration and allowance of all claims remaining in the application are respectfully requested.

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